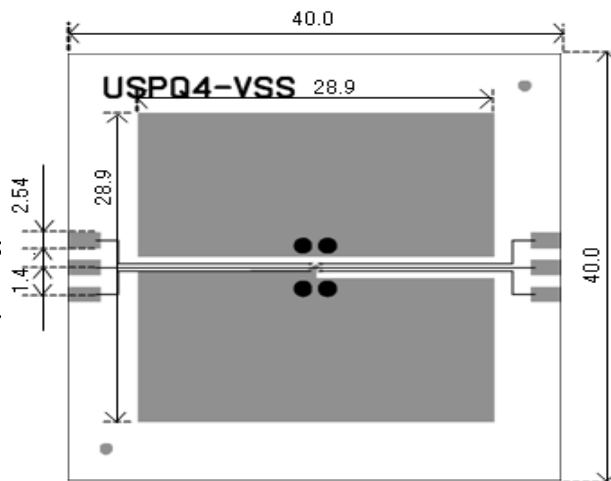


● **USPQ-4B03 Power Dissipation**

Power dissipation data for the USPQ-4B03 is shown in this page.
 The value of power dissipation varies with the mount board conditions.
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board Dimensions: 40 x 40 mm (1600mm²)
- Board Structure: 4 Copper Layers
 Each layer is connected to the package heat-sink and terminal pin No.1.
 Each layer has approximately 800mm² copper ar
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	550	181.82
85	220	

